

Amendments to the specification

Please replace the original Abstract with the following revised Abstract:

ABSTRACT OF THE DISCLOSURE

A coaxial via structure is adapted to transmit high speed signals or high intensity current through conductive layers of an electronic device carrier ~~is provided~~. The coaxial via structure comprises a central conductive track and an external conductive track separated by a dielectric material and is positioned in a core of the electronic device carrier or in the full thickness of the electronic device. The coaxial via structure can be combined with a stacked via structure so as allow efficient transmission of high speed signals across the electronic device carrier when a manufacturing process limits the creation of a full coaxial via structure across the entire electronic device carrier.